Product Change Notification

Change Notification #: 115787 - 00

Change Title: Intel® Thermal Solution BXTS13X,
PCN 115787-00,
Transport Media, Product Material, Retail Box Artwork update

Date of Publication: August 30, 2017

Key Characteristics of the Change:

Transport Media, Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	September 30, 2017

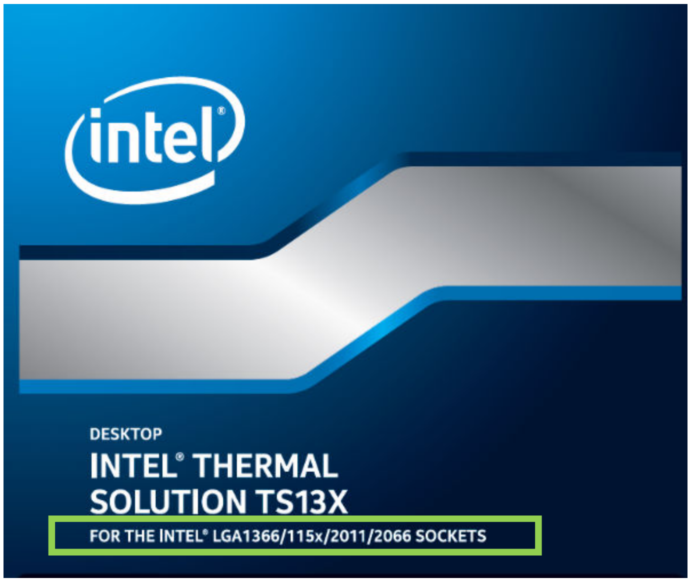
Description of Change to the Customer:

Intel Corporation is implementing changes to the Intel® Thermal Solution BXTS13X retail box Artwork and description. The retail bot part number will change from G94213-997 to J72369-001. See examples of the specific changes for each side of the retail box packaging below:

Current Box Front Panel

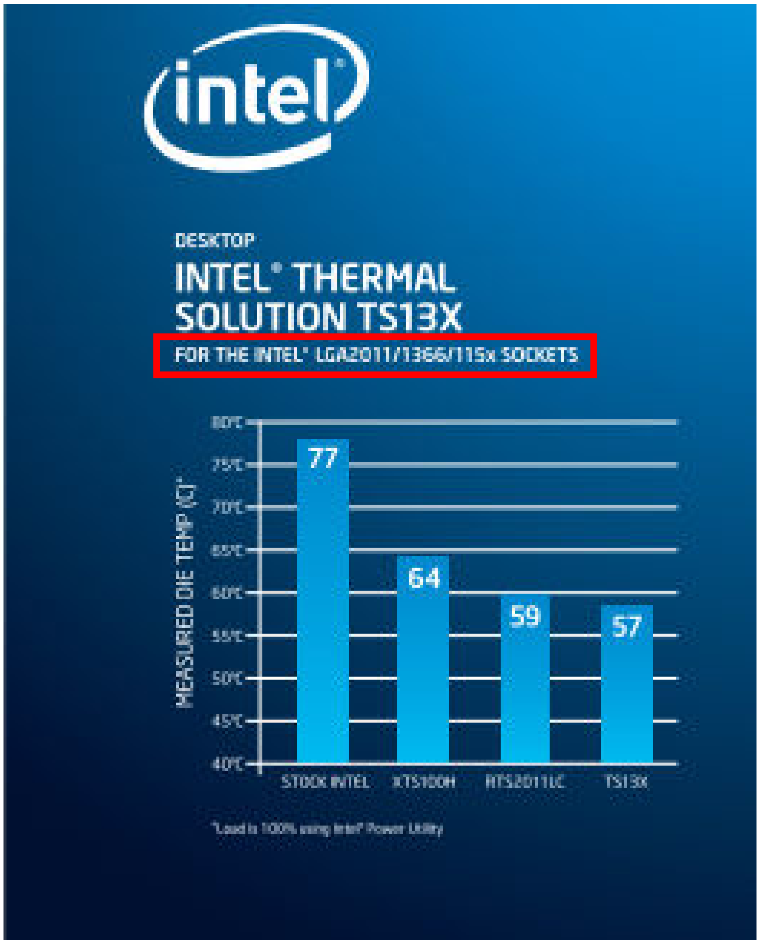
REMOVED: "For the Intel® LGA2011/1366/115x SOCKETS"

New Box Front Panel



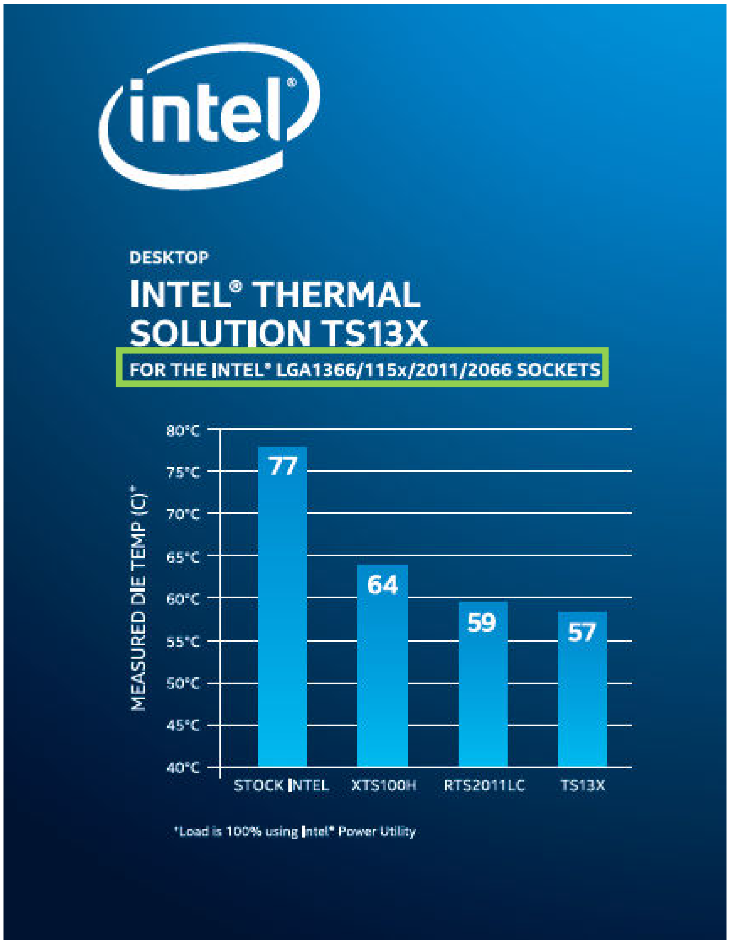
REPLACED W/: "FOR THE INTEL® LGA 1366/115x/2011/2066 SOCKETS"

Current Left Side Panel



PRODUCT NAME/TAG LINE:
REMOVED: “For the Intel® LGA2011/1366/115x SOCKETS”

New Left Side Panel



PRODUCT NAME/TAG LINE:
REPLACED W/: “FOR THE INTEL® LGA 1366/115x/2011/2066 SOCKETS”

Current Right Side Panel

DESKTOP

INTEL® THERMAL SOLUTION TS13X

FOR THE INTEL® LGA2011/1366/115x SOCKETS

- Supports Intel® Processors with the LGA2011/1366/115x Sockets
- Zero Maintenance Sealed Liquid Cooling
- S4-pin Pulse Width Modulation (PWM) Fan Control
- Robust Design Meets Intel's Stringent Shock/Drop Testing[1]
- Three-Year Limited Warranty

<u>PRODUCT NAME/TAG LINE:</u>
REMOVED: “For the Intel® LGA2011/1366/115x SOCKETS”

<u>MARKETING BULLETS:</u>

1. REMOVED: “Supports Intel® Processors with the LGA2011/1366/115x Sockets”
2. REMOVED: Three Year Limited Warranty

New Right Side Panel

DESKTOP

INTEL® THERMAL SOLUTION TS13X

FOR THE INTEL® LGA1366/115x/2011/2066 SOCKETS

- Zero Maintenance Sealed Liquid Cooling
- S4-pin Pulse Width Modulation (PWM) Fan Control
- Robust Design Meets Intel's Stringent Shock/Drop Testing[1]

<u>PRODUCT NAME/TAG LINE:</u>
REPLACED W/: “FOR THE INTEL® LGA 1366/115x/2011/2066 SOCKETS”

Current Top Panel

DESKTOP

INTEL® THERMAL SOLUTION TS13X

FOR THE INTEL® LGA2011/1366/115X SOCKETS

- Supports Intel® Processors with the LGA2011/1366/115x Sockets
- Zero Maintenance Sealed Liquid Cooling
- S4-pin Pulse Width Modulation (PWM) Fan Control
- Robust Design Meets Intel's Stringent Shock/Drop Testing¹
- Three-Year Limited Warranty

PRODUCT NAME/TAG LINE:
REMOVED: "For the Intel® LGA2011/1366/115x SOCKETS"

MARKETING BULLETS:
REMOVED all bullets

New Top Panel

DESKTOP

INTEL® THERMAL SOLUTION TS13X

FOR THE INTEL® LGA1366/115x/2011/2066 SOCKETS

PRODUCT NAME/TAG LINE:
REPLACED W/: "FOR THE INTEL® LGA 1366/115x/2011/2066 SOCKETS"

Current Bottom Panel

This box contains an Intel® Thermal Solution designed for use with Intel® processors in the LGA2011/1366/115x socket. The full text of a Three-Year Limited Warranty and installation instructions are contained in the booklet enclosed.

Cette boîte contient une solution thermique Intel® conçue pour être utilisée avec les processeurs Intel® dans la prise LGA2011/1366/115x. Le texte complet de la garantie limitée de 3 ans et les instructions d'installation sont fournis dans la brochure ci-jointe.

Diese Packung enthält eine Intel® Thermolösung zur Verwendung mit Intel® Prozessoren im LGA2011/1366/115x-Sockel. Der vollständige Text der beschränkten Dreijahresgarantie und Installationsanweisungen sind in der beigelegten Dokumentation enthalten.

Esta caja contiene una solución térmica de Intel® diseñada para ser usada con los procesadores de Intel® en el enchufe LGA2011/1366/115x. El texto completo de la garantía limitada de 3 años y las instrucciones de instalación están contenidos en el folleto que se incluye con el producto.

Esta caixa contém uma Solução Térmica Intel®, criada para uso em processadores Intel® no soquete LGA2011/1366/115x. O texto completo da garantia limitada de três (3) anos e as instruções de instalação se encontram na brochura que acompanha o produto.

Questa confezione contiene una soluzione termica Intel® appositamente ideata per i processori Intel® nel socket LGA2011/1366/115x. Il testo completo della garanzia limitata di tre anni e le istruzioni di installazione sono inclusi nell'opuscolo allegato.

To pudełko zawiera urządzenie odprowadzające ciepło Intel® przeznaczone do użytku z procesorami Intel® w podstawce LGA2011/1366/115x. Pełny tekst Trzyletniej Ograniczonej Gwarancji oraz instrukcję obsługi zamieszczono w załączonej książeczce.

В этой упаковке содержится система охлаждения серии Intel® Thermal Solution, предназначенная для использования с процессорами Intel®, устанавливаемыми в разъем (сокет) LGA2011/1366/115x. Полный текст трехлетней ограниченной гарантии и инструкции по установке приводятся в буклете.

本產品包裝內含專為 LGA2011/1366/115x 插槽中的 Intel® 處理器而設計的 Intel® 散熱模組。三年有限保固保單全文以及安裝說明載於此處隨附的手冊中。

本产品包装内含专为 LGA2011/1366/115x 插座内的 Intel® 处理器而设计的 Intel® 散热模块。三年有限保修保单全文及安装说明载于此处随附的小册子。

이 박스에는 LGA2011/1366/115x 소켓에 장착되는 Intel® 프로세서용으로 설계된 Intel® 서멀 솔루션이 들어 있습니다. 동봉된 안내서에는 3년 보증서 전문과 설치 지침이 포함되어 있습니다.

本ボックスには、LGA2011/1366/115xソケットのインテル®プロセッサーとの使用を目的として設計されたインテル®サーマル・ソリューションが入っています。3年間限定保証書とインストール説明書は、同梱されたブックレットに含まれています。

G94213-997

New Bottom Panel

Contents: Intel® Thermal Solution, three-year Limited Warranty and Instructions.

Inhalt: Intel® Thermolösung, beschränkter Dreijahresgarantie und Installationsanweisungen.

Contient : Solution thermique Intel®, garantie limitée de trois ans et consignes.

Contenuto della confezione: soluzione termica Intel®, certificato di garanzia limitata di tre anni e istruzioni.

Zawartość: rozwiązanie Intel® z urządzeniem odprowadzającym ciepło, tekst trzyletniej ograniczonej gwarancji oraz instrukcja obsługi.

Conteúdos: Solução térmica Intel®, garantia limitada de três anos e manual de instruções.

Contenido: solución térmica Intel®, garantía limitada de tres años e instrucciones.

Содержимое упаковки: процессор Intel® с системой охлаждения серии Thermal Solution, талон ограниченной гарантии сроком три года и инструкции.

內容物： Intel® 散熱模組、三年有限保固及說明書

包装内容：英特尔® 散热模块、三年有限保修单、使用说明。

内容物：インテル® サーマル・ソリューション, 3 年限定保証, 取扱説明書

이 박스에는 인텔® 서멀 솔루션이 들어 있습니다. 또한 3년 보증서와 설치 지침이 포함되어 있습니다.

J72369-001

1. Updated Warranty languages (12) to new translations for Thermal only product. "Contents: Intel® thermal Solution, three-year Limited Warranty and instructions."
2. Updated P/N to J72369-001

Current Back Panel

INTEL® THERMAL SOLUTION TS13X[2]

Intel® Active Thermal Solution for Intel® Core™ processor families with the LGA2011/1366/115x sockets

FAN SPEEDS	800 – 2,200 RPM (4 wire PWM)
FAN DIMENSIONS	120 mm x 120 mm x 25 mm
FAN CFM	73.84 CFM
UNIT NOISE LEVEL	21dBA @ 800 RPM, 35dBA @ 2,200 RPM
RADIATOR DIMENSIONS	150 mm x 118 mm x 37 mm
PUMP Z HEIGHT	31 mm
TOTAL THERMAL SOLUTION WEIGHT	820 grams
COOLING LIQUID	Propylene Glycol
THERMAL INTERFACE MATERIAL	Dow Corning TC-1996

Custom designed 120 mm fan

Improved higher efficiency pump

Copper cold plate for maximum heat dissipation

BOX CONTENTS:

- Intel® Thermal Solution TS13X Cooler
- 120 mm x 25 mm custom built fan
- Dual thermal interface material pillow pack
- Intel LGA2011/1366/115x mounting kits
- Installation guide

See label on side of box for product code information.

[1] For more information refer to the booklet enclosed.

[2] The actual thermal solution enclosed may differ from this image.

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BOX CONTENT BULLETS:

1. Removed 3rd bullet (Dual thermal interface material pillow pack). Replaced with "Thermal Interface Material pre-applied"
2. Removed 4th bullet & replaced with "Intel LGA1366/115x/2011/2066 mounting kits"

CHART:
Changed "Dow Corning TC-1996" to "Dow Corning TC-5630"

PRODUCT NAME/TAG LINE:
REMOVED: "with the Intel® LGA2011/1366/115x SOCKETS"

REGULATORY MARKS:
Reordered from left to right:
CE, No Wheelie Bin, Chasing Arrows, PAP21, Green Dot, Triman, Japanese recycle

Removed year from Copyright bullet

New Back Panel

INTEL® THERMAL SOLUTION TS13X[2]

Intel® Active Thermal Solution for Intel® Core™ processor families for the Intel® LGA1366/115x/2011/2066 sockets

Fan Speeds	800 – 2,200 RPM (4 wire PWM)
Fan Dimensions	120 mm x 120 mm x 25 mm
Fan CFM	73.84 CFM
Unit Noise Level	21dBA @ 800 RPM, 35dBA @ 2,200 RPM
Radiator Dimensions	150 mm x 118 mm x 37 mm
Pump Z Height	31 mm
Total Thermal Solution Weight	820 grams
Cooling Liquid	Propylene Glycol
Thermal Interface Material	Dow Corning TC-5630

Custom designed 120 mm fan

Improved higher efficiency pump

Copper cold plate for maximum heat dissipation

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Reordered from left to right:

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PRODUCT NAME/TAG LINE:

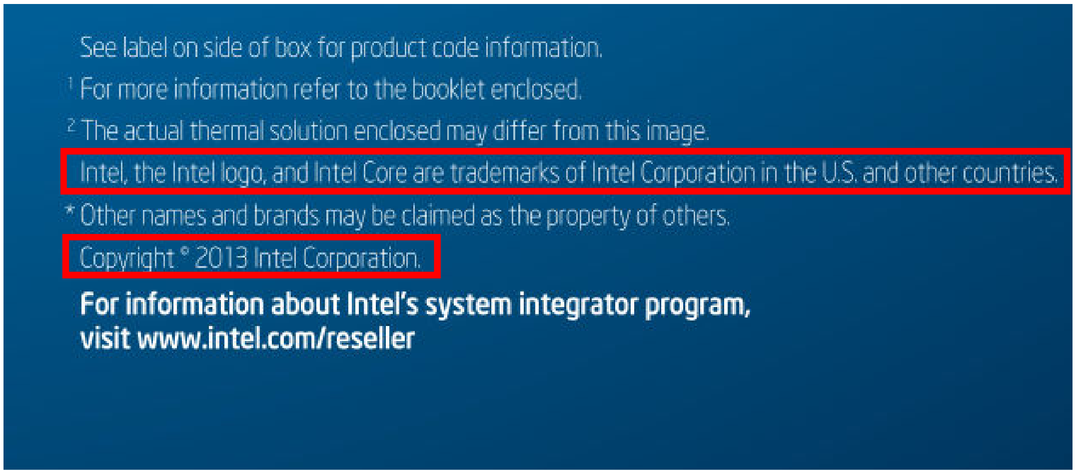
REPLACED W/: "FOR THE INTEL® LGA 1366/115x/2011/2066 SOCKETS"

BOX CONTENT BULLETS:

Removed 3rd bullet (Dual thermal interface material pillow pack). Replaced with "Thermal Interface Material pre-applied"

Removed 4th bullet & replaced with "Intel LGA1366/115x/2011/2066 mounting kits"

Current Back Panel



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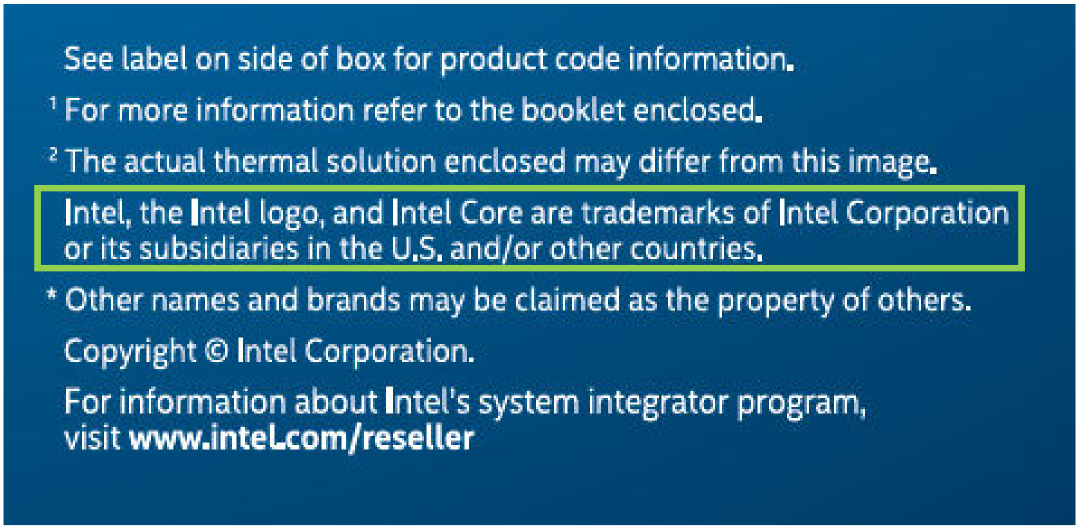
New Back Panel



See label on side of box for product code information.

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Changed trademark notice to: "Intel, the Intel logo, and Intel Core are trademarks of Intel Corporation or its subsidiaries in the U.S. and/or other countries."

Removed year from Copyright bullet

Customer Impact of Change and Recommended Action:

This packaging change will affect the retail box. There is no change to the form, fit or function of the label, manual, processor or the thermal solution, therefore no action is needed by customers. Customers may see a mix of products until inventory has been depleted.

Products Affected / Intel Ordering Codes:

Marketing Name	Product Code	MM#
Intel® Thermal Solution BXTS13X, Retail	BXTS13X929672	929672

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
August 30, 2017	00	Originally Published PCN

Product Change Notification

115787 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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